

PROCESSING METHOD OF WAFER

ABSTRACT

A processing method of a wafer includes a water-soluble resin application step of applying a water-soluble resin to a front surface of the wafer, a modified-layer forming step of applying a laser beam of a wavelength that has transmissivity for the wafer, from a back surface of the wafer with a focal point of the laser beam positioned corresponding to each of dividing lines inside the wafer, thereby forming modified layers along the each of the dividing lines, a resin removing step of removing the wafer-soluble resin from the front surface of the wafer, and a dividing step of applying an external force to the wafer, thereby dividing the wafer into individual device chips.

[FIG. 9B]